



EN71PL032A Base MCP

Stacked Multi-Chip Product (MCP) Flash Memory and RAM

32 Megabit (2M x 16-bit) CMOS 3.0 Volt-only Simultaneous Operation Page Mode Flash Memory and

16 Megabit (1M x 16-bit) Pseudo Static RAM

Distinctive Characteristics

MCP Features

- Power supply voltage of 2.7 V to 3.3V
- High performance
 - 70 ns
- Package
 - 7 x 9 x 1.2mm 56 ball FBGA
- Operating Temperature
 - 25°C to +85°C

General Description

The EN71PL series is a product line of stacked Multi-Chip Product (MCP) packages and consists of:

- EN29PL032A (Simultaneous Read/Write) Flash memory die.
- Pseudo SRAM.

For detailed specifications, please refer to the individual datasheets listed in the following table.

Device	Document
NOR Flash	EN29PL032A
Pseudo SRAM	ENPSL16

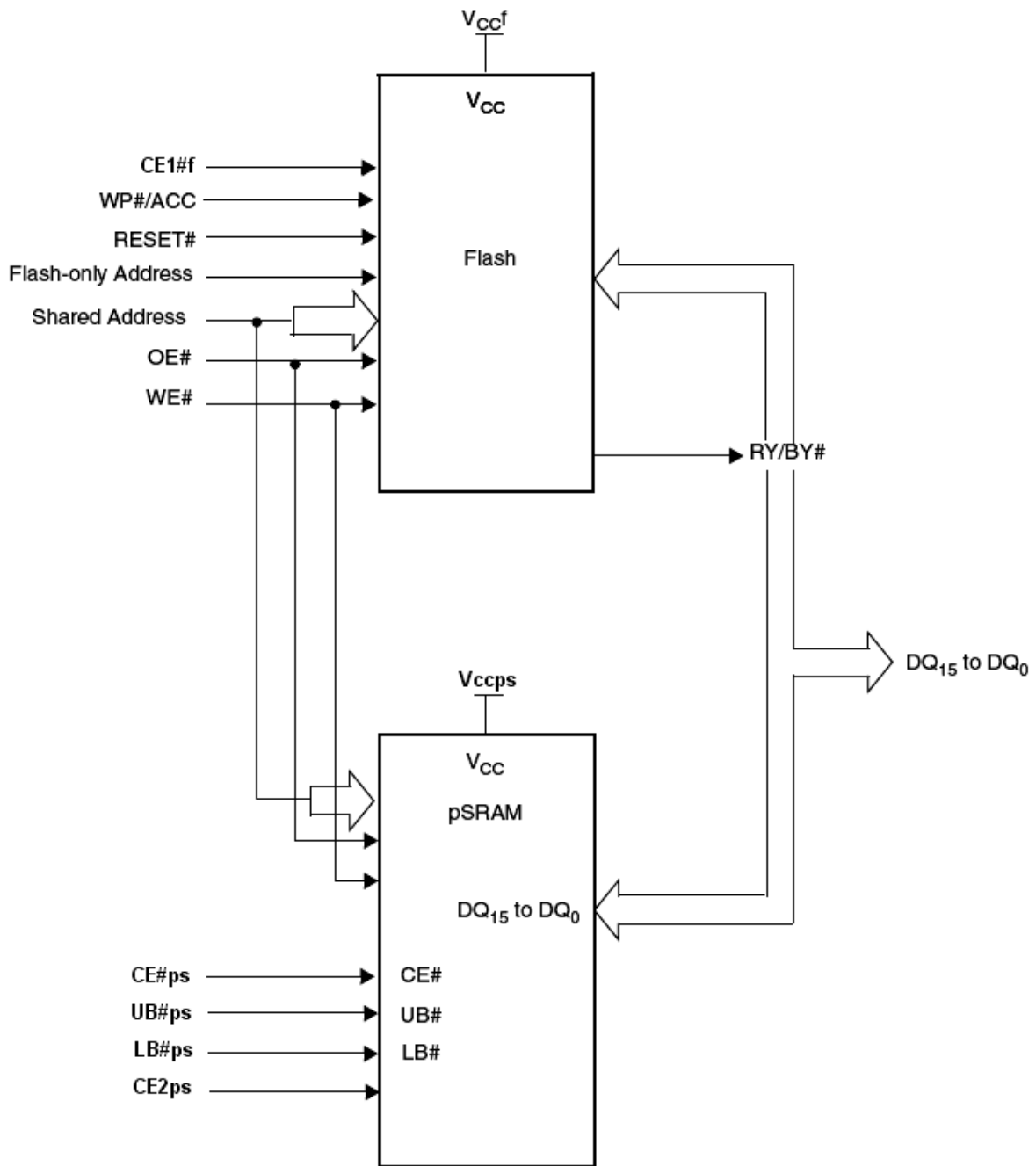
Product Selector Guide

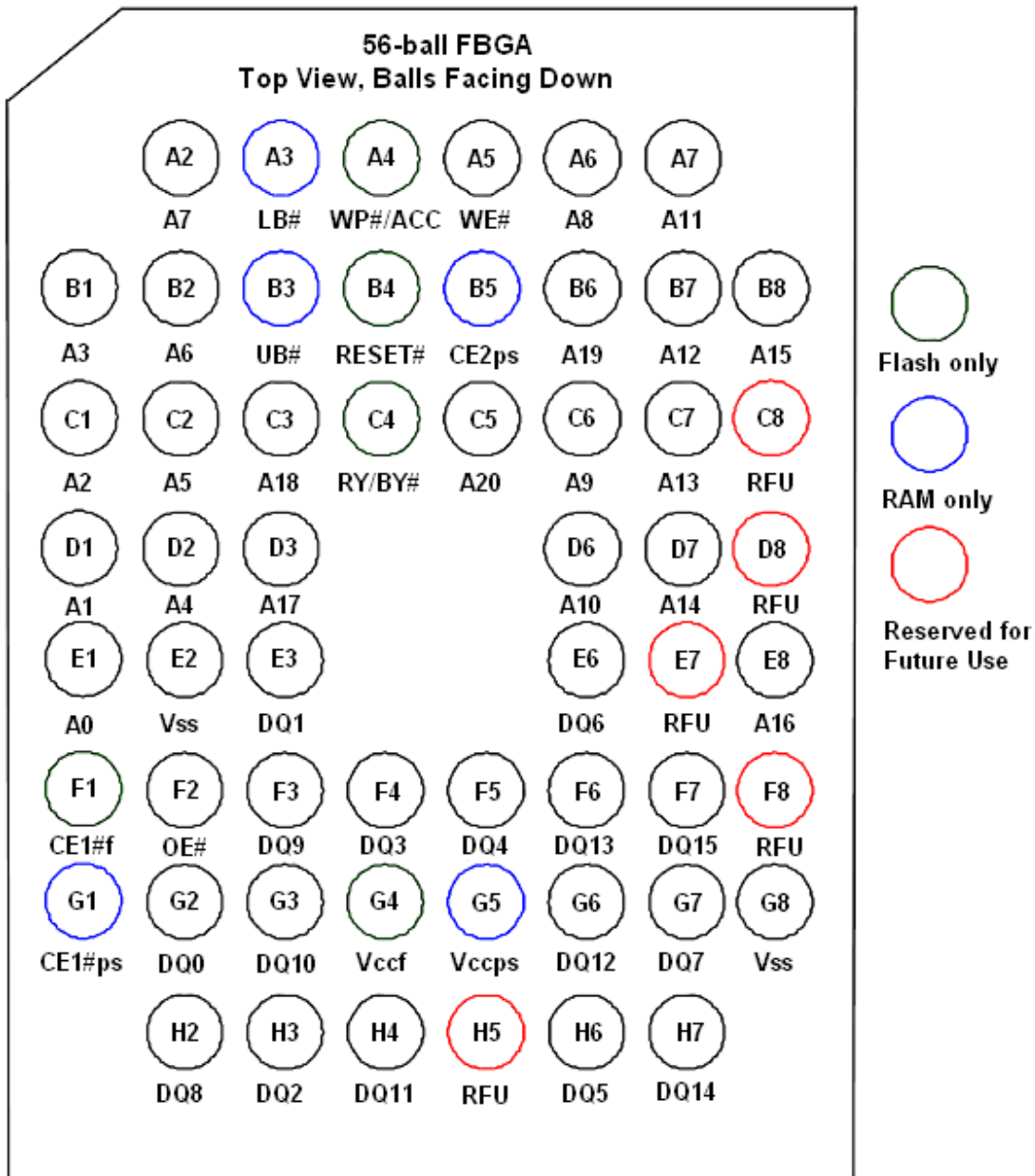
32Mb Flash Memory

Device-Model#	EN71PL032A0A	pSRAM density	16M pSRAM
Flash Access time	70ns	pSRAM Access time	70ns
Page read Access time	25ns	pSRAM Page read Access time	25ns
Package	56 FBGA		



MCP Block Diagram



Connection Diagram


MCP	Flash-only Addresses	Shared Addresses
EN71PL032A0A	A20	A19 – A0

Note: A9 = VID for HV Autoselect mode is not available for MCP product.

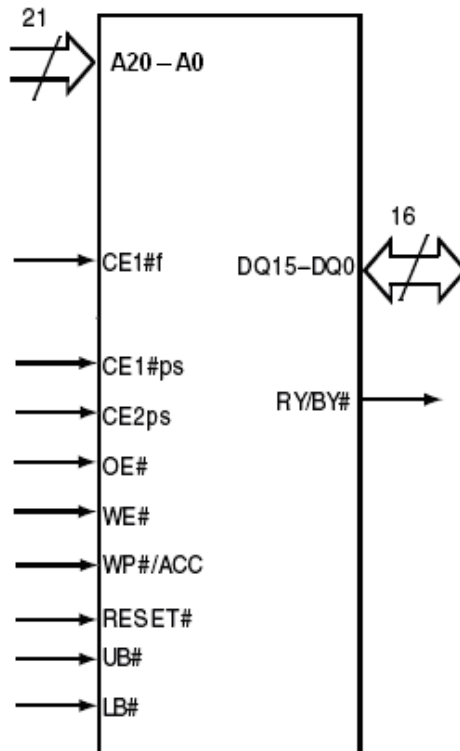


Pin Description

Signal	Description
A20–A0	21 Address Inputs (Common)
DQ15–DQ0	16 Data Inputs/Outputs (Common)
CE1#f	Chip Enable 1 (Flash)
CE1#ps	Chip Enable 1 (pSRAM)
CE2ps	Chip Enable 2 (pSRAM)
OE#	Output Enable (Common)
WE#	Write Enable (Common)
RY/BY#	Ready/Busy Output (Flash)
UB#	Upper Byte Control (pSRAM)
LB#	Lower Byte Control (pSRAM)
RESET#	Hardware Reset Pin, Active Low (Flash)
WP#/ACC	Hardware Write Protect/Acceleration Pin (Flash)
V _{ccf}	Flash 3.0 volt-only single power supply
V _{ccps}	pSRAM Power Supply
V _{ss}	Device Ground (Common)
NC	Pin Not Connected Internally

Note: A9 = VID for HV Autoselect mode is not available for MCP product.

Logic Symbol





Purpose

Eon Silicon Solution Inc. (hereinafter called “Eon”) is going to provide its products’ top marking on ICs with < cFeon > from January 1st, 2009, and without any change of the part number and the compositions of the ICs. Eon is still keeping the promise of quality for all the products with the same as that of Eon delivered before. Please be advised with the change and appreciate your kindly cooperation and fully support Eon’s product family.

Eon products’ Top Marking

cFeon

cFeon Top Marking Example:

cFeon

Part Number: XXXX-XXX

Lot Number: XXXXX

Date Code: XXXXX

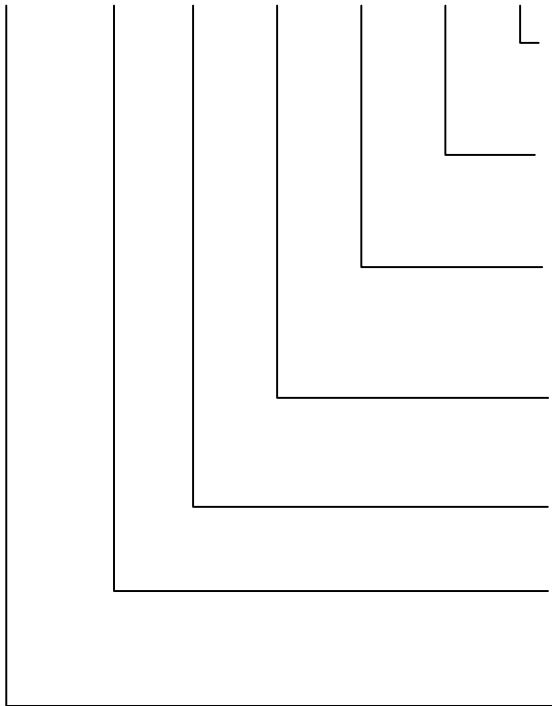
For More Information

Please contact your local sales office for additional information about Eon memory solutions.



ORDERING INFORMATION

EN71PL032 A0 A — 70 C W P



PACKAGING CONTENT

P = RoHS compliant

TEMPERATURE RANGE

W = Wireless (-25°C to +85°C)

PACKAGE

C =56-Ball Fine Pitch Ball Grid Array (FBGA)
0.80mm pitch, 7mm x 9mm package

SPEED

70 = 70ns

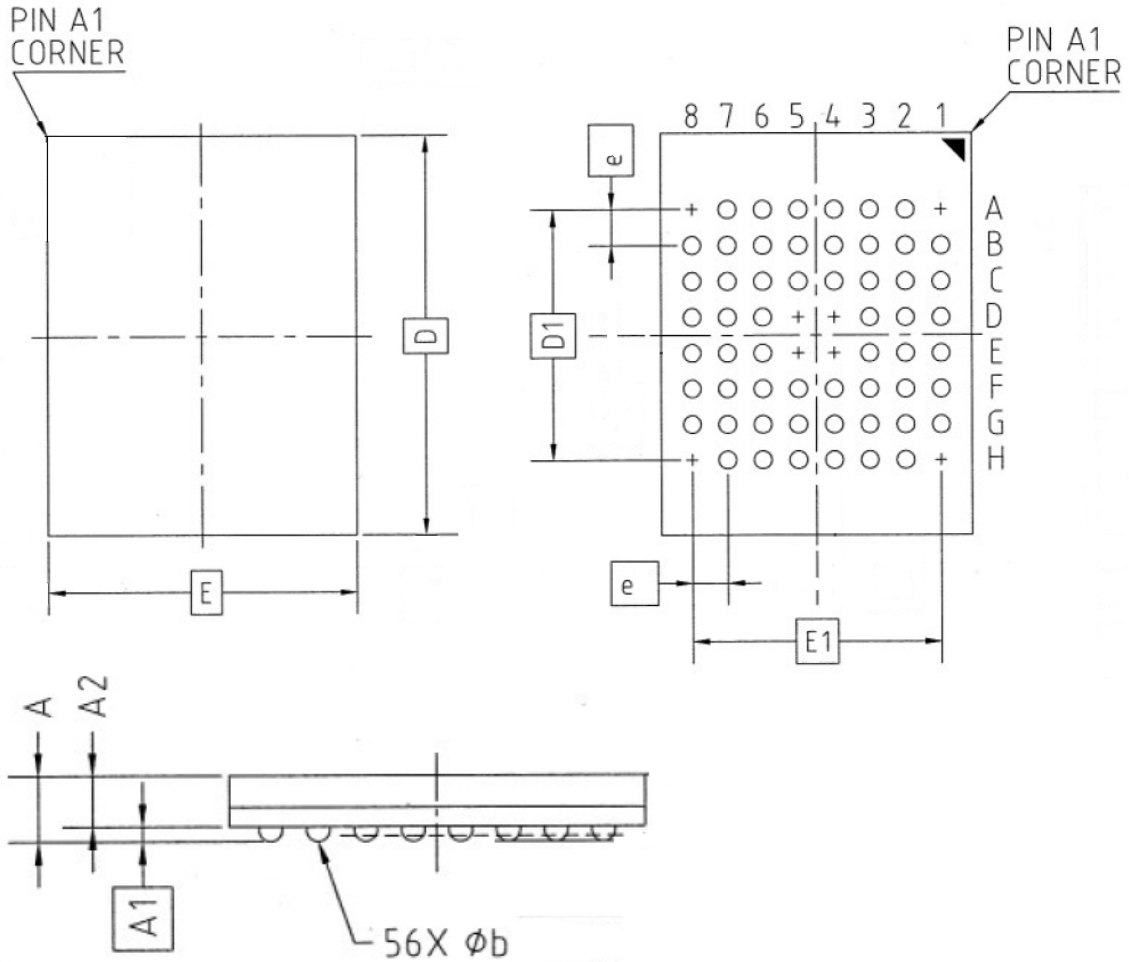
A = version identifier

pSRAM density

A0 = 16M pSRAM

BASE PART NUMBER

EN = Eon Silicon Solution Inc.
71PL = Multi-chip Product (MCP)
3.0V Simultaneous Read/Write,
Page Mode Flash Memory and RAM
032 = 32 Megabit (2M x 16)

PACKAGE MECHANICAL
**56-ball Fine-Pitch Ball Grid Array (FBGA) 7 x 9 mm Package,
pitch: 0.8mm, ball: 0.4mm**


SYMBOL	DIMENSION IN MM		
	MIN.	NOR	MAX
A	---	---	1.20
A1	0.25	0.30	0.35
A2	0.80	---	0.95
D	8.95	9.00	9.05
E	6.95	7.00	7.05
D1	---	5.60	---
E1	---	5.60	---
e	---	0.80	---
b	0.35	0.40	0.45

Note : Controlling dimensions are in millimeters (mm).



Revisions List

Revision No	Description	Date
A	Initial Release	2010/11/15